	BLE STAN		4507.40					4.4		
RATING	VOLTAGE OPERATING		STO		CURRENT			1A		
	TEMPERATUR	RE RANGE	-35°C TO + 85°C (NOTE 1) 20% TO 80% (NOTE 2)		TEMPERATU	JRE RANGE	<u> </u>	-10°C TO + 60°C(N	OTE	OTE 3)
	OPERATING HUMIDITY RA APPLICABLE	NGE			STORAGE HUMIDITY R. APPLAICABL	HUMIDITY RANGE		40% TO 70%(NOTE :		3)
	CONNECTOR		1 0510 .0 1 050 1		1	IMP CONTACT		DF13-2630SCFA (05)		
			0050	IEIOAE				DF13-3032SCFA(05)	
				IFICAT	101/15				1	_
	TEM		TEST METHOD			RE	QUIF	REMENTS	QT	1
	RUCTION KAMINATION	TVISHALLY	AND BY MEASURING INSTRU	IMENT	IACCOL	RDING TO	DRA	WING	X	T
MARKING		CONFIRMED VISUALLY.				1			 	+
FLECTR	IC CHARA	CTERIS	STICS							1 '
			DC OR 1000 Hz).		30m Ω	MAX.			Ιχ	Τ
INSULATION		100V DC.			500MΩ	500MΩ MIN.				+
RESISTANCE VOLTAGE PROOF		500V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.			X	+
						TO LEAGUE TO THE STATE OF THE S				Ŀ
	VICAL CH			OTIC:::						_
MECHANICAL OPERATION		50TIMES INSERTIONS AND EXTRACTIONS.			② NO	① CONTACT RESISTANCE: 30mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			X	
		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			② NO	 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			Х	T
		ACCELAERATION OF 490 m/s ² , 11 ms DUARATION, SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES; 18 TIMES IN TOTAL.			ION, ① NO S; ② NO	 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				
FNVIRO	NMENTAL		CTERISTICS			FAITIS.				
RAPID CHA			ATURE -55→ 5 TO 35→85-	→ 5 TO 35 °	°C ① COI	NTACT RE	SIST	ANCE: 30mΩ MAX.		Τ
TEMPERATURE		TIME $30 \rightarrow 5 \text{ TO } 15 \rightarrow 30 \rightarrow 5 \text{ TO } 15 \text{ min}$ UNDER 5 CYCLES.			3 NO	 ② INSULATION RESISTANCE: 500MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			X	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			② INS ③ NO	 CONTACT RESISTANCE: 30mΩ MAX. INSULATION RESISTANCE: 500MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				
RESISTANCE TO SOLDERING HEAT		1) FLOW SOLDERING 250±5°CMAX, FOR 10 SECONDS. 2) SOLDERING IRONS: :290±10°C, FOR 3 SECONDS			EXCES	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			Х	
SOLDERABILITY		SOLDERI 215±5°C	ERED AT SOLDER TEMPERATURE, 5°C			SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				
NOTE2:NO NOTE3:APP BEF	CONDENSING PLY TO THE CO FORE PCB ON	TEMPERA' 3. ONDITION BOARD AF	ERTION DURATION, 3 SEC TURE RISE BY CURRENT. OF LONG TERM STORAGE TER PCBBOARD, OPERA D FOR INTERM STORAGE	E FOR UN	PERATURE A	AND				
	IT D	ESCRIPTION	N OF REVISIONS	D	ESIGNED			CHECKED		ATE
COUN		_:e: -!				 		W		
Δ	Unless otherwise specifid , refer to JIS C 5402.					APPROVI	-	KI. AKIYAMA	11. 03.	
Δ						CHECKED		HK. UMEHARA 1		11. 03. 2
Δ						DESIGNED)3.
Δ										
<u>M</u> Unless otl				Т		DRAWN	1	ST. SATO	11.0)3.
<u>M</u> Unless otl	ualification Te	st AT:Assı	ırance Test X:Applicable Te	st	DRAWIN		N	ST. SATO ELC4-081816		03.
<u>M</u> Unless otl			ırance Test X:Applicable Te		DRAWIN ART NO.					03.